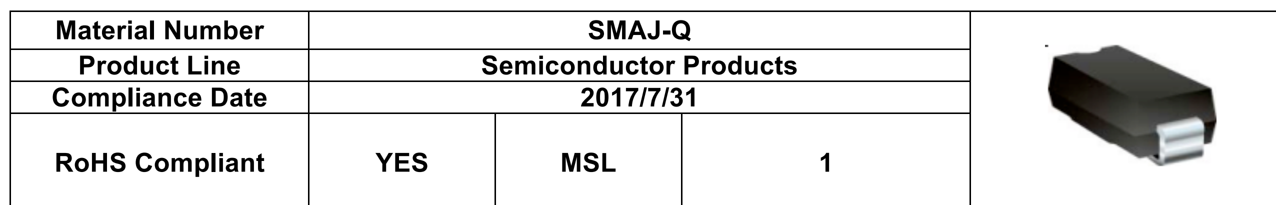
MATERIAL DECLARATION SHEET



Material Number	SMAJ-Q		
Product Line	Semiconductor Products		
Compliance Date	2017/7/31		
RoHS Compliant	YES	MSL	1

No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Dice	Silicon	0.001330	Silicon	7440-21-3	60.18	1.28	2.128
				Phosphorus	7723-14-0	0.01	0.0002	
				Boron	7440-42-8	0.01	0.0002	
				Nickel	7440-02-0	14.8	0.315	
				Lead	7439-92-1	12.5	0.266	
				Silicon dioxide	7631-86-9	10.0	0.213	
				Aluminum oxide	1344-28-1	2.5	0.0532	
2	High-melting point Solder paste	Solder paste	0.002003	Tin	7440-31-5	5	0.16	3.203
				Lead	7439-92-1	92.5	2.963	
				Silver	7440-22-4	2.5	0.08	
3	Lead frame	Copper	0.0275	Copper	7440-50-8	99.8	43.89	43.978
				Iron	7439-89-6	0.15	0.066	
				Phosphorus	7723-14-0	0.05	0.022	
4	Molding compound	Epoxy material	0.031035	Silicon dioxide	14808-60-7	76	37.72	49.632
				Epoxy resin	25928-94-3	9	4.467	
				Phenolic resin-A,B	9003-35-4	8	3.971	
				Hydroxide metal	-	6	2.978	
				Carbon black	1333-86-4	1	0.496	
5	Plating	Matte-100% tin	0.000663	Tin	7440-315	100	1.06	1.06
		Total weight	0.062531					

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This Document was updated on: 2017/7/31

Important remarks:

1. **It is the responsibility of the user to verify they are accessing the latest version.**
2. **7(a) Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)**
3. **7(c)-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.**

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